

DEVICE DISSIPATION (W)

12.0

10.0

8.0

6.0

4.0

2.0

0

10

20

30

40

50

60

70

80

INFINITE HEAT SINK 12°C W

STAYER V 7 COPPER HEAT SINK 30°C W

6 SD IN COPPER FOIL P.C. BOARD 35°C W

4 SD IN COPPER FOIL P.C. BOARD 38°C W

2 SD IN COPPER FOIL P.C. BOARD 45°C W

0.4 SD IN COPPER FOIL P.C. BOARD

73°C W

FREE AIR 82°C W

T_A - AMBIENT TEMPERATURE (°C)

